

NOTES:

1. MATERIAL:

HOUSING:LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

3. DATE-CODE LOCATION. AND DATE-CODE *YMDLS*
 IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)

4. LGA1366 TO BE INDICATED IN THIS AREA.

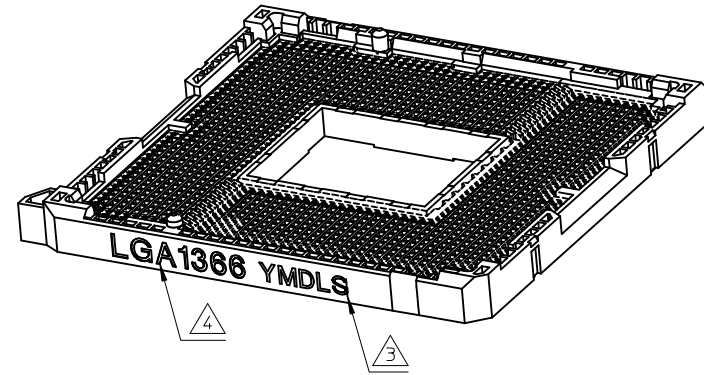
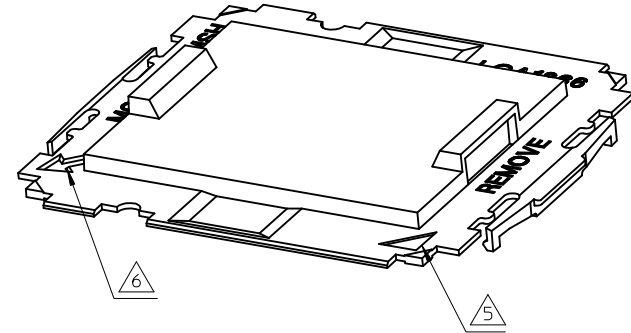
5. SOCKET PIN 1 INDICATOR.

6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

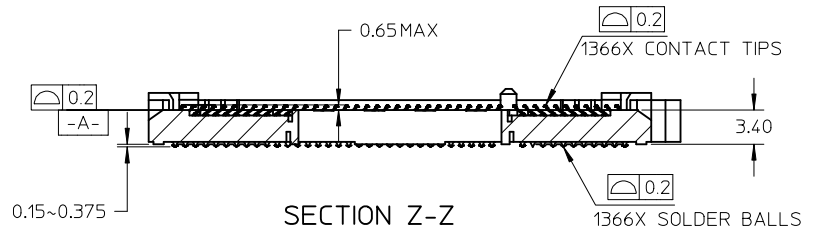
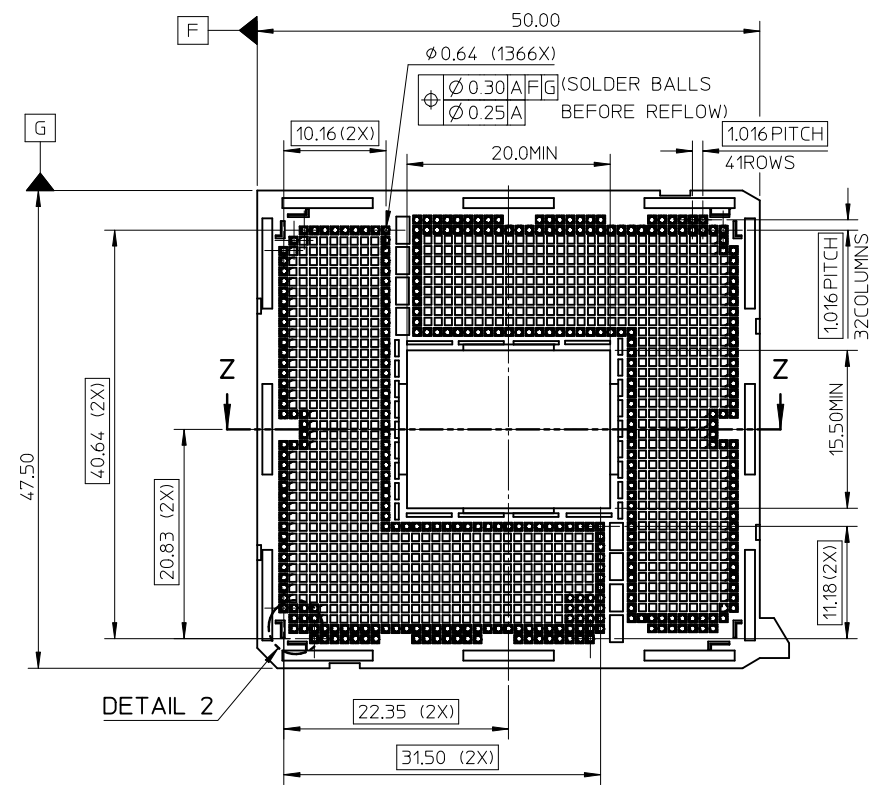
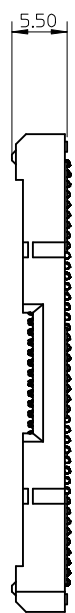
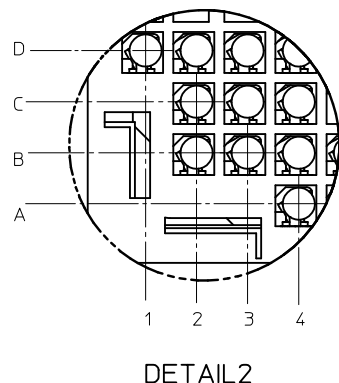
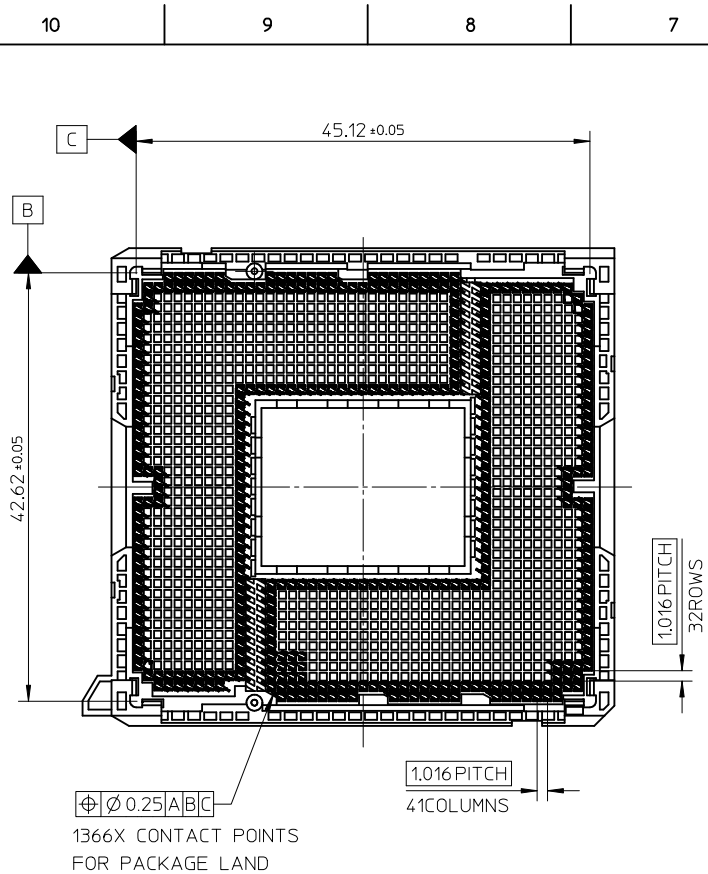
8. PRODUCT PACKAGE PK-47594-003 APPLIES.

9. THE PARTS 475940001/0002 COMPLIANT TO RoHS
 DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.



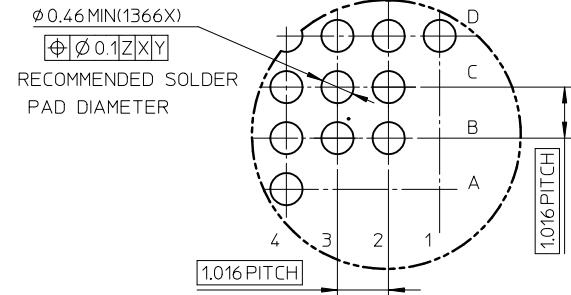
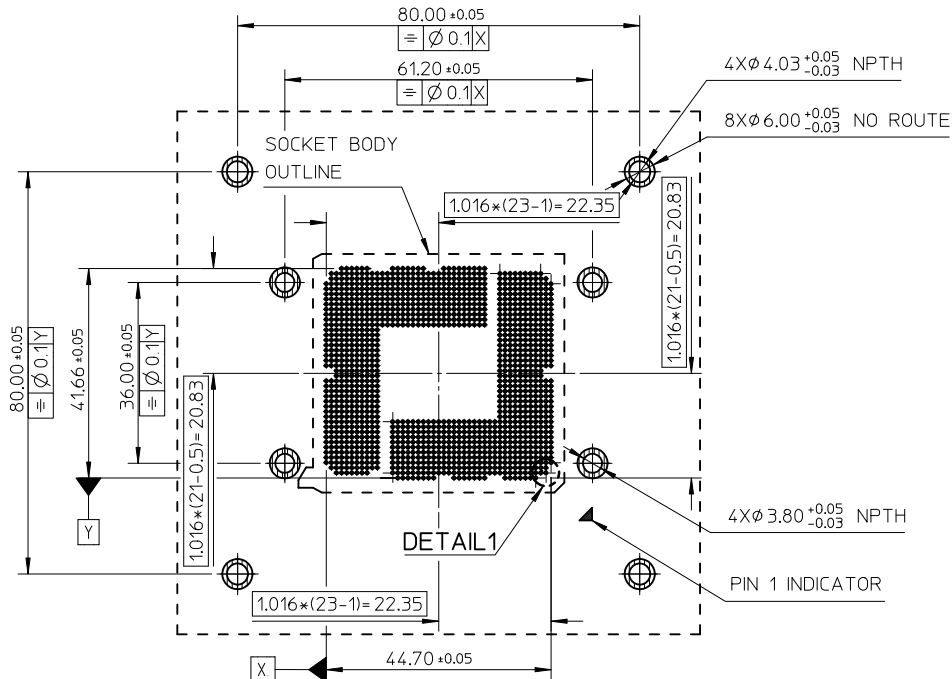
LGA1366 SOCKET PART NUMBER LIST				
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT
475940002	GENERAL	30u*(0.76um)	LEAD FREE	YES
475940001	GENERAL	15u*(0.38um)		

ENTER DESCRIPTION EC NO: SH2012-0177 DRWN: ZHANG11 CHKD: APPR: AYIN 2011/12/07 2011/12/14	DESCRIPTION REV 2011/12/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		$F_A=0$ $F_B=0$ $F_C=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1°	MM ONLY	2:1	METRIC	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: WFDENG DATE: 2008/09/16 CHECKED BY: JKACHLIC DATE: 2008/09/16 APPROVED BY: AYIN DATE: 2010/10/22 MATERIAL NO. SEE TABLE	TITLE: LGA1366 SOCKET FULL ASSEMBLY MOLEX MOLEX INCORPORATED DOCUMENT NO. SD-47594-001	SHEET NO. 1 OF 3	
				SIZE: A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

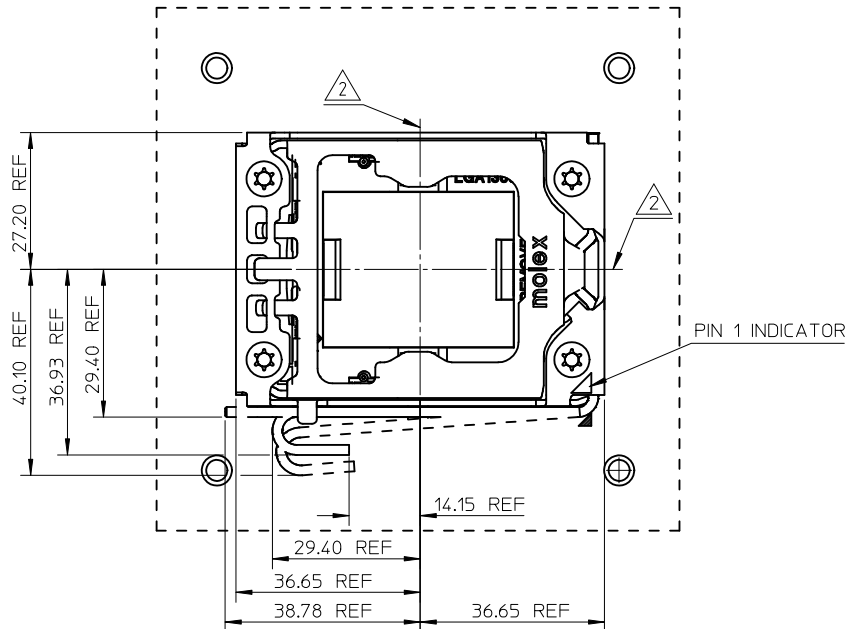
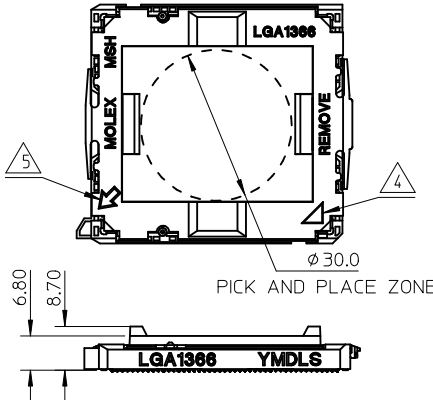


ENTER DESCRIPTION EC NO: SH2012-0177 DRWN: ZHANG11 CHKD: APPR: AYIN	REV 2011/12/14	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			$\nabla_{\sqrt{A}}=0$	mm	INCH	MM ONLY	2:1	METRIC		
			$\nabla_{\sqrt{B}}=0$	4 PLACES ± ---	± ---	DRAWN BY	DATE	TITLE	LGA1366 SOCKET FULL ASSEMBLY	
			$\nabla_{\sqrt{C}}=0$	3 PLACES ± ---	± ---	WFDENG	2008/09/16		MOLEX INCORPORATED	
			$\nabla_{\sqrt{D}}=0$	2 PLACES ± 0.20	± ---	CHECKED BY	DATE			
				1 PLACE ± 0.25	± ---	JKACHLIC	2008/09/16			
				ANGULAR ± 1 °		APPROVED BY	DATE			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		AYIN	2010/10/22			
						MATERIAL NO.		DOCUMENT NO.		SHEET NO.
						SEE TABLE		SD-47594-001		2 OF 3
						SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
						A3				

10 9 8 7 6 5 4 3 2 1



RECOMMEND PCB LAYOUT THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



SOCKET ON PCB(FOR REFERENCE ONLY)
LOAD PLATE IS NOT LOCKED

- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
 - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
 - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 - SOCKET PIN 1 INDICATOR.
 - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
 - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.

ENTER DESCRIPTION EC NO: SH2012-0177 DRWN: ZHANG11 CHKD: APPR: AYIN	DESCRIPTION 2011/12/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
		$\nabla_F=0$ $\nabla_E=0$ $\nabla_D=0$	mm	INCH	MM ONLY	1:1	METRIC			
REV	REV	DESCRIPTION	4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE		
			3 PLACES	± ---	± ---	WFDENG	2008/09/16	LGA1366 SOCKET FULL ASSEMBLY		
			2 PLACES	± 0.20	± ---	CHECKED BY	DATE			
			1 PLACE	± 0.25	± ---	JKACH LIC	2008/09/16			
			ANGULAR ± 1°		APPROVED BY	DATE	MOLEX MOLEX INCORPORATED			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		AYIN	2010/10/22	DOCUMENT NO.		SHEET NO.	
			SEE TABLE		MATERIAL NO.		SD-47594-001		3 OF 3	
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

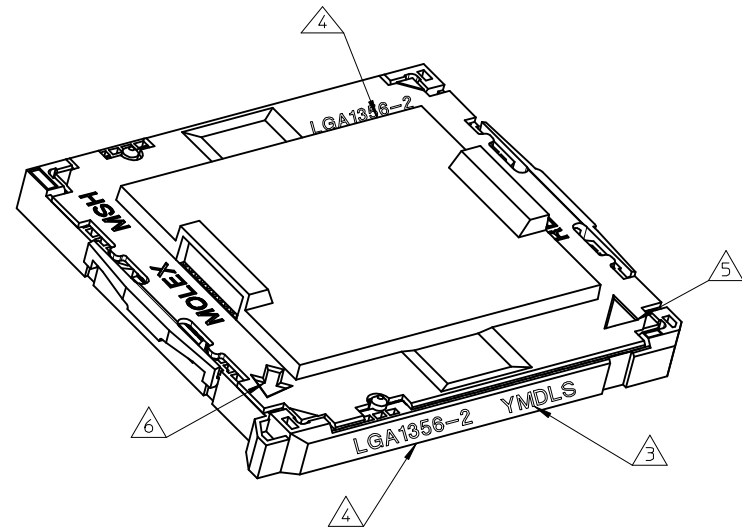
SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

- 3. DATE-CODE LOCATION. AND DATE-CODE *YMDLS* IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)
- 4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

5. SOCKET PIN 1 INDICATOR.

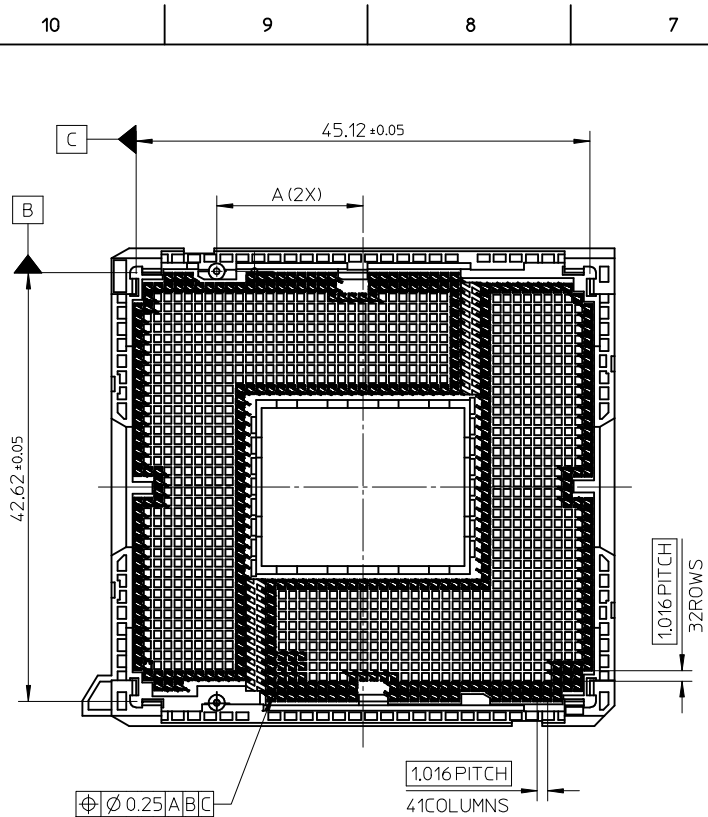
6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

- 7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.
- 8. PRODUCT PACKAGE PK-47594-003 APPLIES.
- 9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

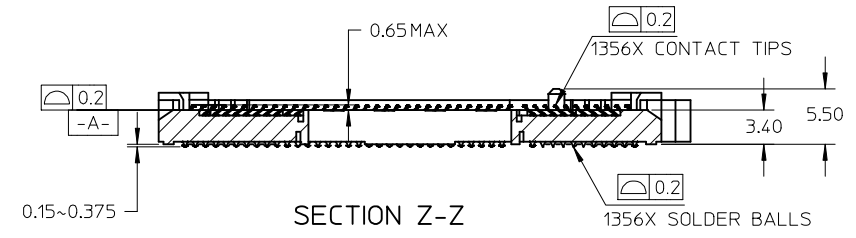
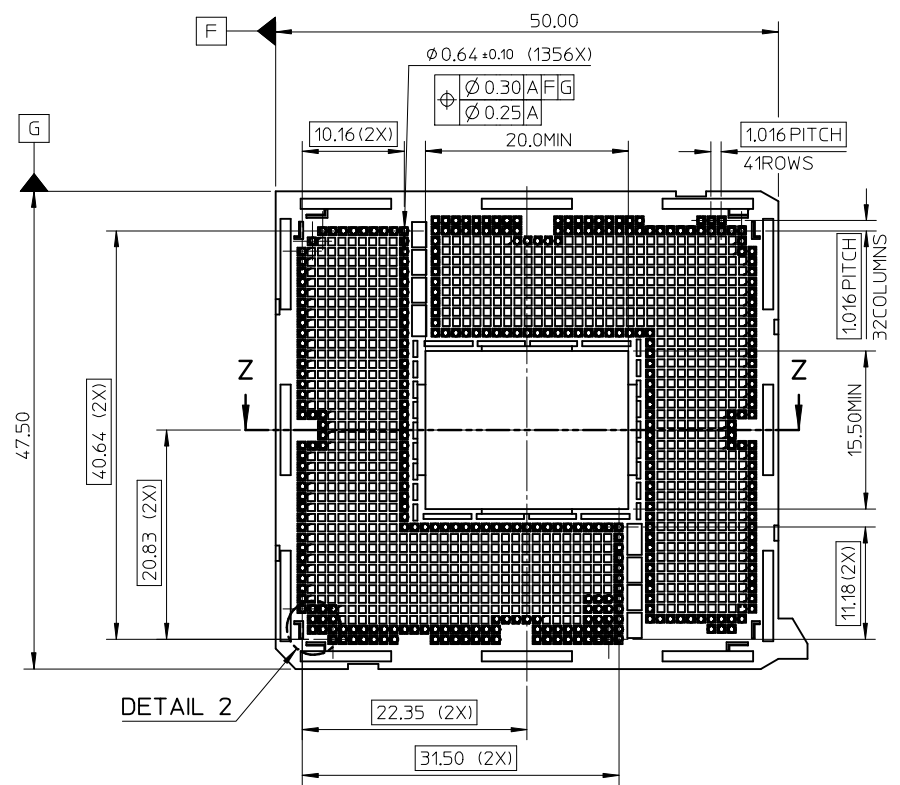
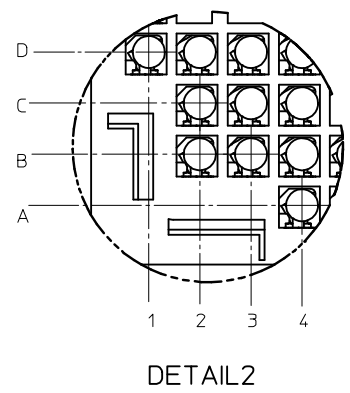


LGA1356 SOCKET PART NUMBER LIST					PART NAME	REMARK
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT		
475943001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-2(B2)	DIM.A=12.85
475943002	GENERAL	30u*(0.76um)				

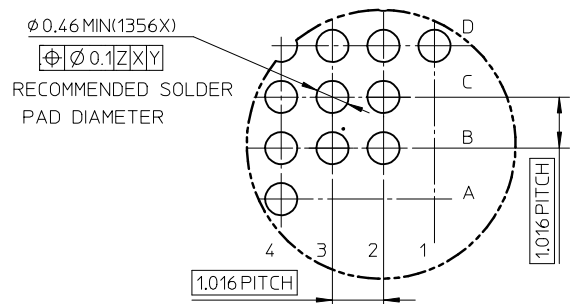
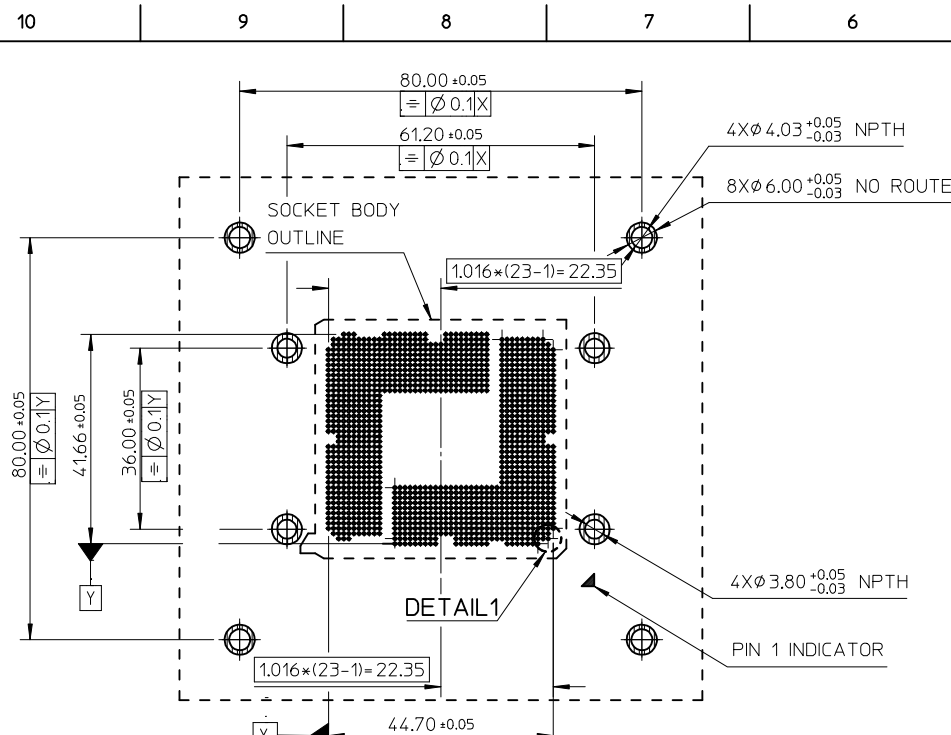
RELEASED EC NO: SH2013-0064 DRWN: YZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$F_A=0$ $F_C=0$ $F_B=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1°	MM ONLY	2:1	METRIC	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: JZHANG11 DATE: 2010/2/10 CHECKED BY: DATE:	TITLE: LGA1356 SOCKET FULL ASSEMBLY		
			APPROVED BY: AYIN DATE: 2011/07/12 MATERIAL NO. SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-47594-100 SHEET NO. 1 OF 3		



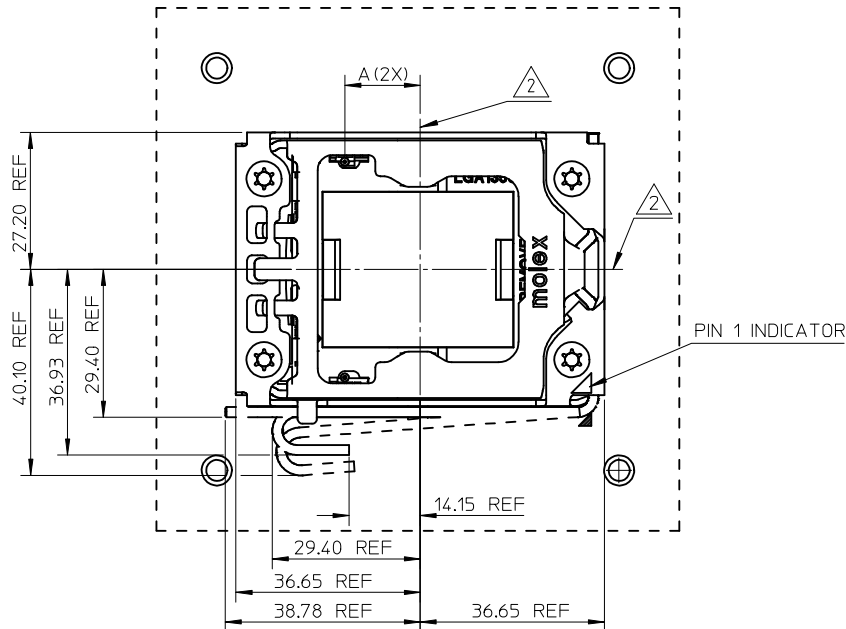
1356X CONTACT POINTS FOR PACKAGE LAND



RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $\nabla = 0$ $\nabla = 0$ $\nabla = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± 0.25	± ---	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	± ---	± ---																		
	3 PLACES	± ---	± ---																		
2 PLACES	± 0.20	± ---																			
1 PLACE	± 0.25	± ---																			
		DRAWN BY: JZHANG11 DATE: 2010/2/10 CHECKED BY:	TITLE LGA1356 SOCKET FULL ASSEMBLY	MOLEX INCORPORATED																	
		APPROVED BY: AYIN DATE: 2011/07/12	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-47594-100	SHEET NO. 2 OF 3																
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	

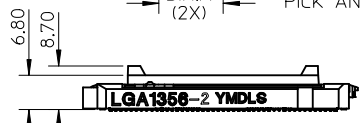
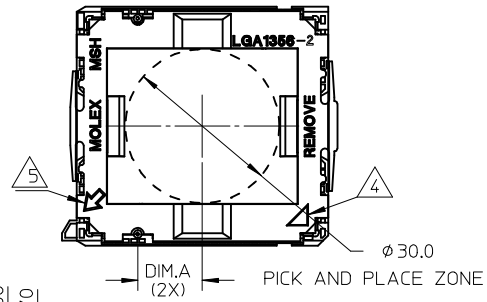


DETAIL1
SCALE 10:1



SOCKET ON PCB(FOR REFERENCE ONLY)
LOAD PLATE IS NOT LOCKED

RECOMMEND PCB LAYOUT THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
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 - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 - SOCKET PIN 1 INDICATOR.
 - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
 - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.

RELEASED IEC NO: SH2013-0064 DRWN: YXZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla F=0$	mm	INCH	MM ONLY	1:1	METRIC	
	$\nabla E=0$	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE	
	$\nabla D=0$	2 PLACES ± 0.20 ± ---	1 PLACE ± 0.25 ± ---	JZHANG11	2010/2/10	LGA1356 SOCKET FULL ASSEMBLY	
	ANGULAR ± 1°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	MOLEX INCORPORATED	
				AYIN	2011/07/12	MOLEX INCORPORATED	
				MATERIAL NO.	DOCUMENT NO.	SD-47594-100	
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
				A3	SHEET NO. 3 OF 3		

NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

3. DATE-CODE LOCATION, AND DATE-CODE "YMDLS"
 IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)

4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

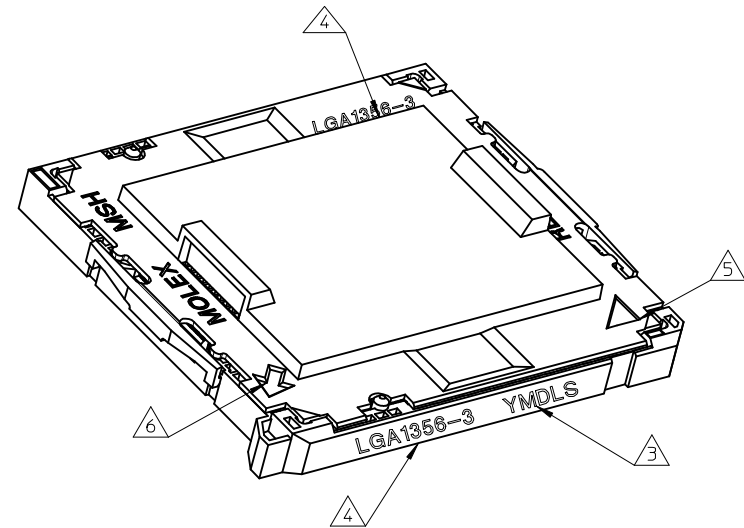
5. SOCKET PIN 1 INDICATOR.

6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

8. PRODUCT PACKAGE PK-47594-003 APPLIES.

9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS
 DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

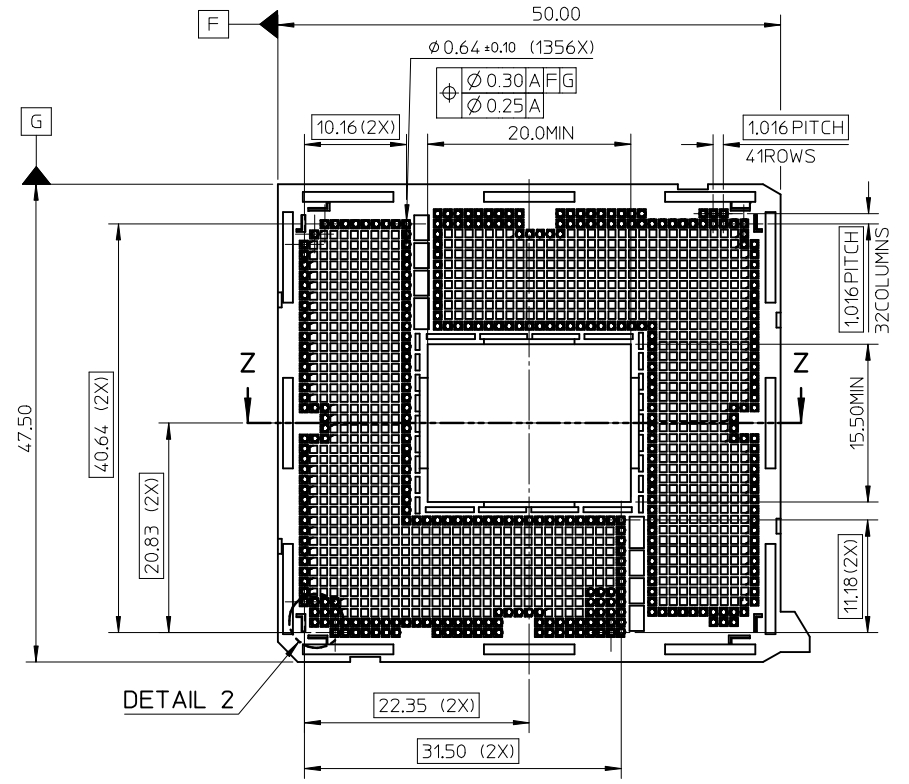
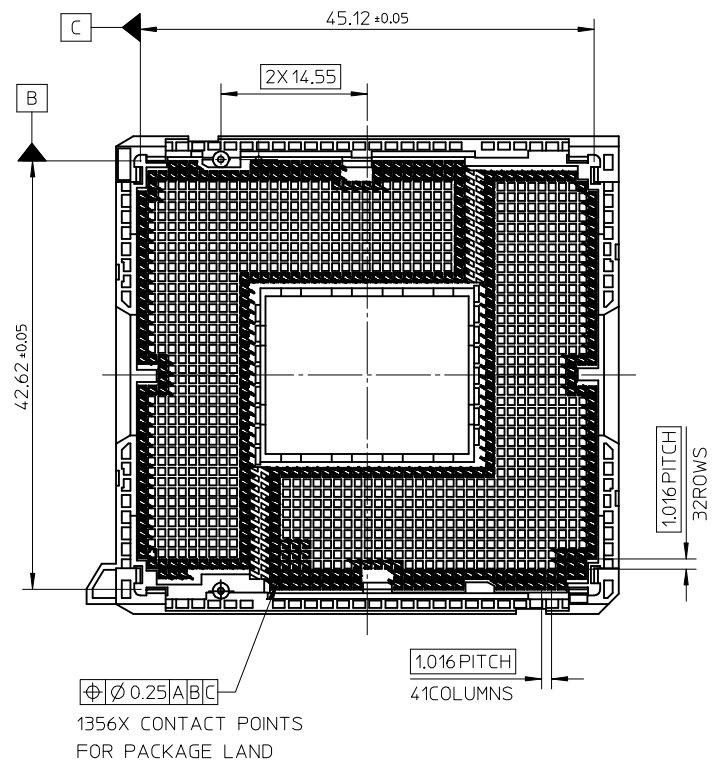


LGA1356 SOCKET PART NUMBER LIST					PART NAME
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT	
475942001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-3(B3)
475942002	GENERAL	30u*(0.76um)			

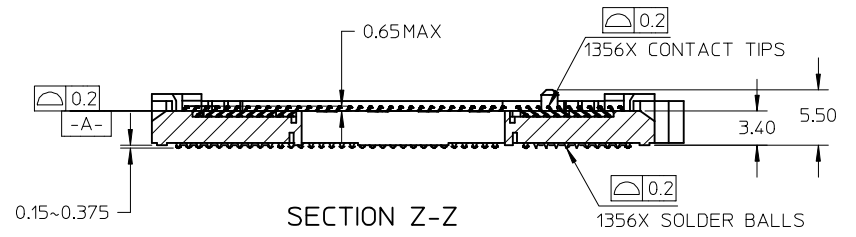
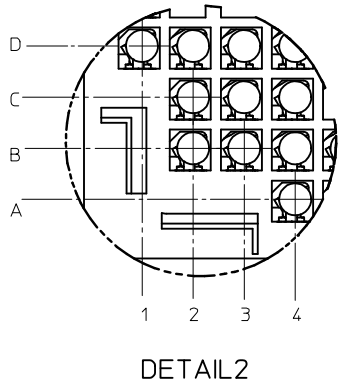
NEW RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/09/24 CH'KD: APPR: AYIN 2013/02/04 REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$F_{\square}=0$	mm	INCH	MM ONLY	2:1	METRIC	
	$F_{\square}=0$	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE	
	$F_{\square}=0$	2 PLACES ± 0.20 ± ---	1 PLACE ± 0.25 ± ---	YXZHENG	2012/09/24	LGA1356-3 SOCKET(B3) FULL ASSEMBLY	
	0 PLACE ± --- ± ---	ANGULAR ± 1 °	CHECKED BY	DATE	molex		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
			AYIN	2013/02/04		SD-47594-200	1 OF 3
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

F E D C B A

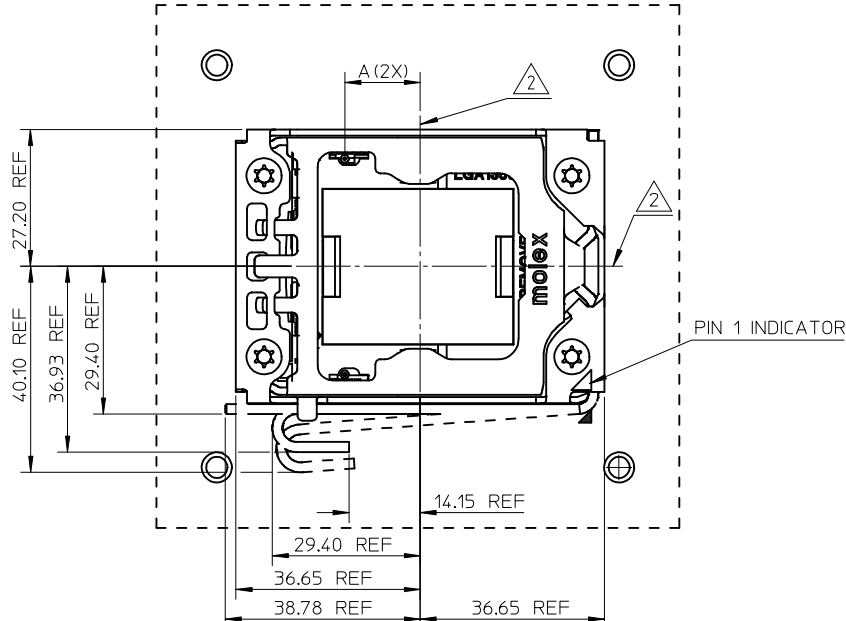
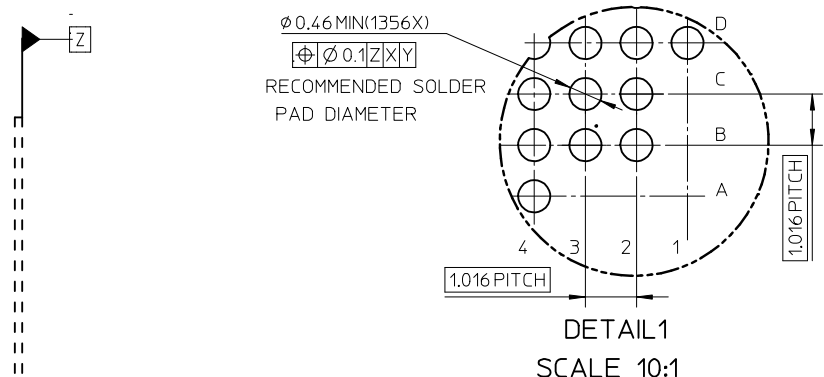
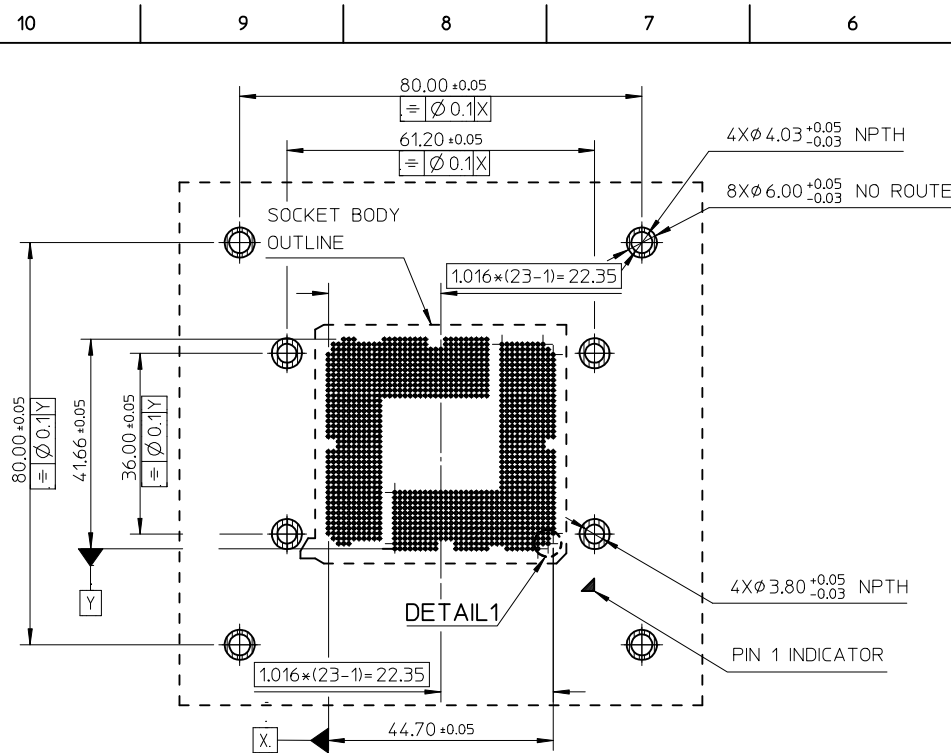


DETAIL 2

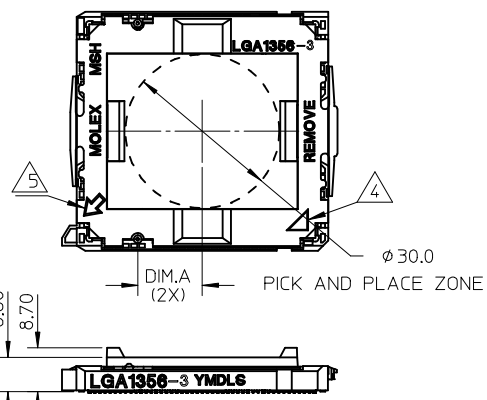


NEW RELEASED EC NO: SHZ013-0064 DRWN: YXZHENG CHKD: APPR: AYIN 2012/09/24 2013/02/04	QUALITY SYMBOLS $F_A=0$ $F_B=0$ $F_C=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± --- ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY DRAWN BY: YXZHENG CHECKED BY: APPROVED BY: AYIN DATE: 2012/09/24 DATE: DATE: 2013/02/04	SCALE 2:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY molex DOCUMENT NO. SD-47594-200 SHEET NO. 2 OF 3
	SEE PAGE 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	SIZE A3				
	1				

9 8 7 6 5 4 3 2 1



RECOMMEND PCB LAYOUT THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
 - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
 - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 - SOCKET PIN 1 INDICATOR.
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NEW RELEASED IEC NO: SH2013-0064 DRWN: YXZHENG CHKD: APPR: AYIN 2012/09/24 2013/02/04	QUALITY SYMBOLS $F_{\Delta} = 0$ $F_{\square} = 0$ $F_{\nabla} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	mm INCH	DRAWN BY YXZHENG	DATE 2012/09/24	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY			
		ANGULAR ± 1 °		APPROVED BY AYIN	DATE 2013/02/04	molex			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE PAGE 1		DOCUMENT NO. SD-47594-200	SHEET NO. 3 OF 3		